IEC 62878-2-602

Edition 1.0 2021-06

INTERNATIONAL STANDARD

NORME INTERNATIONALE

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Device embedding assembly technology – Part 2-602: Guideline for stacked electronic module – Evaluation method of inter-module electrical connectivity

Techniques d'assemblage avec appareil(s) intégré(s) – Partie 2-602: Lignes directrices pour un empilement de modules électroniques – Méthode d'évaluation de la connectivité électrique entre modules

IEC 62878-2-602:2021-06(en-fr)

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DEVICE EMBEDDING ASSEMBLY TECHNOLOGY –

Part 2-602: Guideline for stacked electronic module – Evaluation method of inter-module electrical connectivity

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International Standard IEC 62878-2-602 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1663/CDV	91/1720/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62878 series, published under the general title *Device embedding assembly technology*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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- amended.

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INTRODUCTION

High-end servers, network systems and smart phones have been driving the electronic assembly technologies for the last couple of decades. Any applications to enable the “Internet of Things” (aka IoT) require new electronic assembly technologies to achieve small size, low energy consumption and robust security in a cost-effective way.

This document is one of a series of guidelines for stacked electronic modules.

DEVICE EMBEDDING ASSEMBLY TECHNOLOGY –

Part 2-602: Guideline for stacked electronic module – Evaluation method of inter-module electrical connectivity

1 Scope

This part of IEC 62878 specifies the requirements and evaluation methods of electrical connectivity. It is applicable to stacked electronic modules.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194-2, *Printed boards design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194-2 apply.

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- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp/

4 General

The 3D electronic module is an electronic module which is integrated and assembled using functional blocks, employing a three-dimensional or stacking method. A stacked electronic module is formed by mounting stackable device assembly technology modules vertically on top of one another. Figure 1 depicts an individual stackable electronic module. Figure 2 depicts three such individual modules into a stacked module.

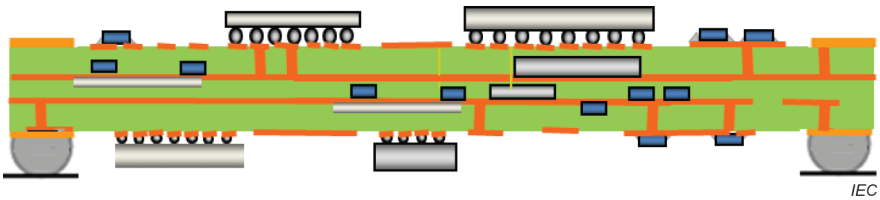

Figure 1 – Stackable electronic module